



Product/Process Change Notice - PCN 23_0095 Rev. A

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This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title:	Qualification of an Alternate Adhesive Material and Molding Compound for Select LFCSP Packages
Publication Date:	17-Jul-2023
Effectivity Date:	18-Sep-2023 <i>(the earliest date that a customer could expect to receive changed material)</i>
Revision Description:	Update current mold material of detailed change description from EN8900 to Ablestik 8900NC.

Description Of Change:

Qualification of an alternate adhesive material and molding compound for select LFCSP packages (LFCSP with non-conductive epoxy).

1. Adhesive material: Hitachi EN4300
2. Mold compound: Sumitomo G700LA.

Reason For Change:

Additional adhesive material and molding compound for increased capability.

Impact of the change (positive or negative) on fit, form, function & reliability:

The devices' fit, form, function and reliability as specified by the Product Data Sheet will be unaffected by these changes. The package outline dimension and lead footprint dimension will remain the same for LFCSP packages.

Product Identification *(this section will describe how to identify the changed material)*

Date Code and Lot number will be used for product identification.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Detailed Change Description

[ADI_PCN_23_0095_Rev_A_Detailed_Change_Description.pdf...](#)

Attachment 2: Type: Qualification Results Summary

[ADI_PCN_23_0095_Rev_A_ADG5207_Qualification_Report.pdf...](#)

Note: If applicable, the device material declaration will be updated due to material change.

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

Appendix A - Affected ADI Models:

Existing Parts - Product Family / Model Number (18)

AD590 / AD590JCPZ-R5	AD590 / AD590JCPZ-RL7	ADG5204 / ADG5204BCPZ-RL7	ADG5206 / ADG5206BCPZ-RL7	ADG5207 / ADG5207BCPZ-RL7
ADG5208 / ADG5208BCPZ-RL7	ADG5209 / ADG5209BCPZ-RL7	ADG5212 / ADG5212BCPZ-RL7	ADG5213 / ADG5213BCPZ-RL7	ADG5233 / ADG5233BCPZ-RL7
ADG5234 / ADG5234BCPZ-RL7	ADG5236 / ADG5236BCPZ-RL7	ADG5404 / ADG5404BCPZ-REEL7	ADG5408 / ADG5408BCPZ-REEL7	ADG5409 / ADG5409BCPZ-REEL7
ADG5413 / ADG5413BCPZ-REEL7	ADG5433 / ADG5433BCPZ-REEL7	ADG5436 / ADG5436BCPZ-REEL7		

Appendix B - Revision History:			
Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	16-Jun-2023	18-Sep-2023	Initial Release
Rev. A	17-Jul-2023	18-Sep-2023	Update current mold material of detailed change description from EN8900 to Ablestik 8900NC.